### Silicon N-Channel MOS FET

# **HITACHI**

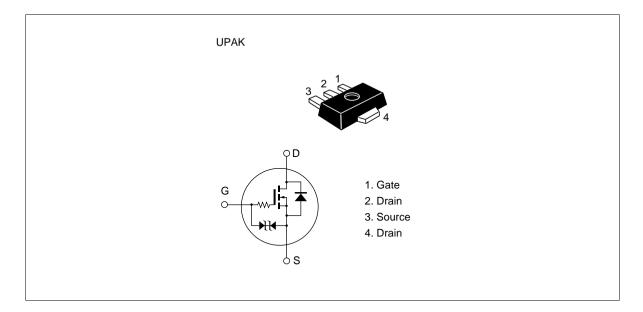
#### **Application**

High speed power switching

#### **Features**

- Low on-resistance
- High speed switching
- Suitable for low voltage operation

#### Outline





### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ unless otherwise specified.)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{\scriptscriptstyle DSS}$	12	V
Gate to source voltage	$V_{GSS}$	±7	V
Drain current	I <sub>D</sub>	2	A
Drain peak current	I <sub>D(pulse)</sub> *1	4	A
Body to drain diode reverse drain current	I <sub>DR</sub>	2	A
Channel power dissipation	Pch*2	1	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

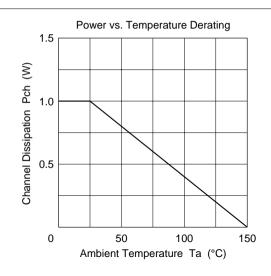
Notes 1. PW  $\leq$  100  $\mu$ s, duty cycle  $\leq$  10%

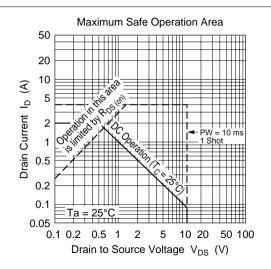
<sup>2.</sup> Value on the almina ceramic board (12.5  $\times$  20  $\times$  0.7 mm)

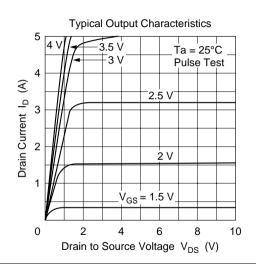
### **Electrical Characteristics** (Ta = 25°C unless otherwise specified.)

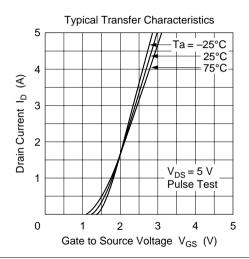
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source cutoff current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 8 \text{ V}, V_{GS} = 0$
Gate to source cutoff current	I <sub>GSS</sub>	_	_	±5	μΑ	$V_{GS} = \pm 6.5 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{\rm GS(off)}$	0.4	_	1.4	V	$V_{DS} = 5 \text{ V}, I_{D} = 100 \mu\text{A}$
Drain to source on resistance (1)	$R_{\text{DS(on)}}1$	_	0.36	0.7	Ω	$V_{GS} = 2.2 \text{ V}, I_D = 0.5 \text{ A}$
Drain to source on resistance (2)	R <sub>DS(on)</sub> 2	_	0.25	0.35	Ω	$V_{GS} = 4 \text{ V}, I_D = 1 \text{ A}$
DC forward transfer admittance	yfs	1	2.5	_	S	$V_{DS} = 5 \text{ V}, I_{D} = 1 \text{ A},$ $\Delta V_{GS} = 0.1 \text{ V}$
Input capacitance	Ciss	_	110	_	pF	$V_{DS} = 5 \text{ V}, V_{GS} = 0,$
Reverse transfer capacitance	Crss	_	30	_	pF	f = 1 MHz
Output capacitance	Coss	_	150	_	pF	_
Turn-on time	t <sub>(on)</sub>	_	500	_	ns	$I_D = 0.2 \text{ A}, V_{GS} = 0,$
Turn-off time	t <sub>(off)</sub>	_	1500	_	ns	Vin = 4 V, $R_L = 51 \Omega$

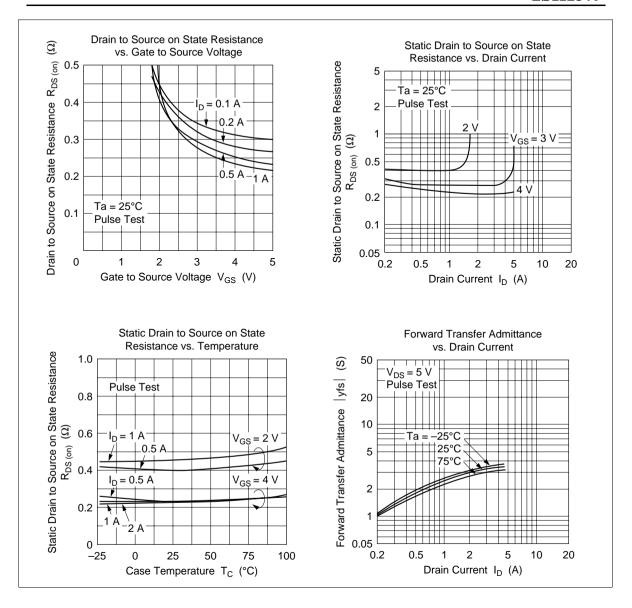
Note 1. Marking is "DY".

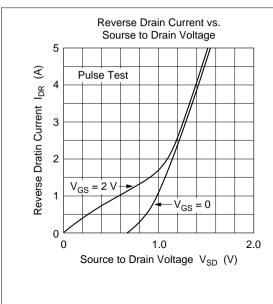


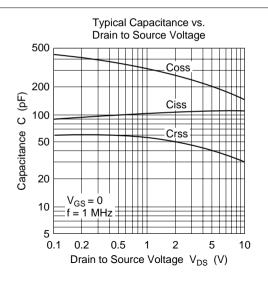


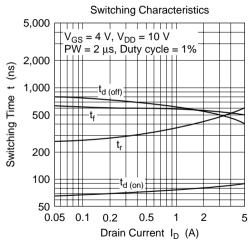




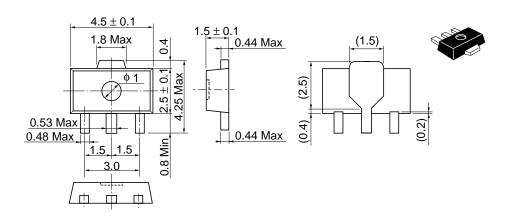








Unit: mm



Hitachi Code	UPAK
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.050 g

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